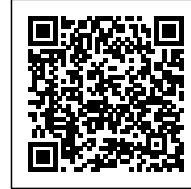


FEEDING EQUIPMENT DIE EJECT UNIT (MANUALLY)

SKU: S3-0087

23.400,00 € excl. VAT



Categories: [Feeding equipment](#), [Modules](#)

BESCHREIBUNG

The needle system of the Die Eject Unit detaches components fixed on a film in order to transfer them to the assembly system. By replacing the manually exchangeable needle system and the wafer frame adapter, a wide range of components are processed from wafers of up to 8 inches in size. The speed of the ejecting needles is synchronized to the assembly system and is component-specific selectable.

The adapted wafer is manually placed on the unit. The Eject Unit is only available for the OurPlant D1.

The Die Eject Unit is available with a needle holder with lid and needle (needle-vacuum system) and a wafer adapter (selectable). By using special optional adaptations also Waffle-Packs can be processed on the module.

MORE INFORMATIONS

Dimensions in mm (W x D x H)

Weight in kg

Max. wafer size in inch / mm

Hub des Nadelsystems in mm 6

Voltage in V 24

Max. current in A 3

Kommunikation

UNICAN

